

Advanced Electronic Packaging

Second Edition

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Contents

Preface to the Second Edition	xv		
Contributors	xvii		
Acronyms	xix		
1. Introduction and Overview of Microelectronic Packaging		1	
<hr/>			
W. D. Brown			
1.1 Introduction	1		
1.2 Functions of an Electronic Package	2		
1.3 Packaging Hierarchy	3		
1.3.1 Die Attach	5		
1.3.2 First-Level Interconnection	5		
1.3.3 Package Lid and Pin Sealing	7		
1.3.4 Second-Level Interconnection	7		
1.4 Brief History of Microelectronic Packaging Technology	8		
1.5 Driving Forces on Packaging Technology	19		
1.5.1 Manufacturing Costs	20		
1.5.2 Manufacturability Costs	20		
1.5.3 Size and Weight	20		
1.5.4 Electrical Design	21		
1.5.5 Thermal Design	21		
1.5.6 Mechanical Design	21		
1.5.7 Manufacturability	22		
1.5.8 Testability	22		
1.5.9 Reliability	23		
1.5.10 Serviceability	23		
1.5.11 Material Selection	23		
1.6 Summary	24		
References	25		
Exercises	26		
2. Materials for Microelectronic Packaging		29	
<hr/>			
W. D. Brown and Richard Ulrich			
2.1 Introduction	29		
2.2 Some Important Packaging Material Properties	29		
2.2.1 Mechanical Properties	30		
2.2.2 Moisture Penetration	30		
2.2.3 Interfacial Adhesion	31		
2.2.4 Electrical Properties	31		
2.2.5 Thermal Properties	33		
2.2.6 Chemical Properties	34		
2.2.7 System Reliability	34		
2.3 Ceramics in Packaging	35		
2.3.1 Alumina (Al ₂ O ₃)	37		
2.3.2 Beryllia (BeO)	39		
2.3.3 Aluminum Nitride (AlN)	40		
2.3.4 Silicon Carbide (SiC)	41		
2.3.5 Boron Nitride (BN)	41		
2.3.6 Glass-Ceramics	42		
2.4 Polymers in Packaging	43		
2.4.1 Fundamentals of Polymers	43		
2.4.2 Thermoplastic and Thermosetting Polymers	45		
2.4.3 Effects of Water and Solvents on Polymers	46		
2.4.4 Some Polymer Properties of Interest	47		
2.4.5 Primary Classes of Polymers Used in Microelectronics	50		
2.4.6 First-Level Packaging Applications of Polymers	55		
2.5 Metals in Packaging	57		
2.5.1 Die Bonding	57		
2.5.2 Chip to Package or Substrate	58		
2.5.3 Package Construction	64		
2.6 Materials Used in High-density Interconnect Substrates	66		
2.6.1 Laminate Substrates	67		
2.6.2 Ceramic Substrates	70		
2.6.3 Deposited Thin-Film Substrates	71		
2.7 Summary	73		
References	73		
Exercises	75		

3. Processing Technologies 77

H. A. Naseem and Susan Burkett

- 3.1 Introduction 77
- 3.2 Thin-Film Deposition 77
 - 3.2.1 Vacuum Facts 78
 - 3.2.2 Vacuum Pumps 79
 - 3.2.3 Evaporation 81
 - 3.2.4 Sputtering 84
 - 3.2.5 Chemical Vapor Deposition 88
 - 3.2.6 Plating 89
- 3.3 Patterning 93
 - 3.3.1 Photolithography 93
 - 3.3.2 Etching 96
- 3.4 Metal-to-Metal Joining 98
 - 3.4.1 Solid-State Bonding 98
 - 3.4.2 Soldering and Brazing 101
- 3.5 Summary 102
 - References 102
 - Exercises 103

4. Organic Printed Circuit Board Materials and Processes 105

Richard C. Snogren

- 4.1 Introduction 105
- 4.2 Common Issues for All PCB Layer Constructions 106
 - 4.2.1 Data Formats and Specifications 106
 - 4.2.2 Computer-Aided Manufacturing and Tooling 107
 - 4.2.3 Panelization 108
 - 4.2.4 Laminate Materials 109
 - 4.2.5 Manufacturing Tolerance Overview 111
- 4.3 PCB Process Flow 112
 - 4.3.1 Manufacture of Inner Layers 112
 - 4.3.2 Manufacture of MLB Structure and Outer Layers 118
 - 4.3.3 Electrical Test 124
 - 4.3.4 Visual and Dimensional Inspection 124
 - 4.3.5 Contract Review 125
 - 4.3.6 Microsection Analysis 125
- 4.4 Dielectric Materials 127
 - 4.4.1 Dielectric Material Drivers 127
 - 4.4.2 Dielectric Material Constructions and Process Considerations 128
- 4.5 Surface Finishes 133

- 4.6 Advanced PCB Structures 134
 - 4.6.1 High-density Interconnection (HDI) or Microvia 134
- 4.7 Specifications and Standards 141
 - 4.7.1 The IPC, a Brief History 141
 - 4.7.2 Relevant Standards to Organic Printed Circuit Boards 141
- 4.8 Key Terms 142
 - References 145
 - Exercises 145

5. Ceramic Substrates 149

Aicha A. R. Elshabini and Fred D. Barlow III

- 5.1 Ceramics in Electronic Packaging 149
 - 5.1.1 Introduction and Background 149
 - 5.1.2 Functions of Ceramic Substrates 149
 - 5.1.3 Ceramic Advantages 150
 - 5.1.4 Ceramic Compositions 150
 - 5.1.5 Ceramic Substrate Manufacturing 151
- 5.2 Electrical Properties of Ceramic Substrates 152
- 5.3 Mechanical Properties of Ceramic Substrates 153
- 5.4 Physical Properties of Ceramic Substrates 154
- 5.5 Design Rules 154
- 5.6 Thin Film on Ceramics 155
 - 5.6.1 Introduction and Background 155
 - 5.6.2 Deposition Techniques 155
 - 5.6.3 Thin-Film Substrate Properties 156
- 5.7 Thick Films on Ceramics 156
 - 5.7.1 Introduction and Background 156
 - 5.7.2 Screen Preparation and Inspection 157
 - 5.7.3 Screen-Printing Process 158
 - 5.7.4 Substrate Cleaning and Process Environment 159
 - 5.7.5 Thick-Film Formulations 159
 - 5.7.6 Heat Treatment Processes for Pastes 160
 - 5.7.7 Thick-Film Metallizations 161
 - 5.7.8 Thick-Film Dielectrics 162
 - 5.7.9 Thick-Film Resistors 162

5.8 Low-Temperature Cofired Ceramics (LTCC) 163

5.8.1 LTCC Technology 163

5.8.2 Tape Handling and Cleanroom Environment 166

5.8.3 Via Formation 167

5.8.4 Via Fill 169

5.8.5 Screen-Printing Considerations for Tape Materials 171

5.8.6 Inspection 172

5.8.7 Tape Layer Collation 172

5.8.8 Lamination 173

5.8.9 Firing 175

5.8.10 Postprocessing 177

5.8.11 Design Considerations 178

5.8.12 Shrinkage Prediction and Control 179

5.9 HTCC Fabrication Process 180

5.9.1 HTCC Process 180

5.9.2 Multilayer ALN 180

5.10 High-Current Substrates 180

5.10.1 Direct Bonded Copper Process 181

5.10.2 Active Metal Brazing (AMB) 182

5.11 Summary 182

References 183

Exercises 184

6. Electrical Considerations, Modeling, and Simulation 187

S. S. Ang and L. W. Schaper

6.1 Introduction 187

6.1.1 When Is a Wire Not a Wire? 187

6.1.2 Packaging Electrical Functions 187

6.2 Fundamental Considerations 188

6.2.1 Resistance 189

6.2.2 Self and Mutual Inductance 194

6.2.3 Capacitance 200

6.2.4 Parameter Extraction Programs 202

6.3 Signal Integrity and Modeling 202

6.3.1 Digital Signal Representation and Spectrum 203

6.3.2 Driver and Receiver Models 205

6.3.3 RC Delay 207

6.4 Transmission Lines 212

6.4.1 Microstrip Transmission Lines 215

6.4.2 Termination Reflections 217

6.4.3 Signal Line Losses and Skin Effect 223

6.4.4 Net Topology 224

6.5 Coupled Noise or Crosstalk 226

6.6 Power and Ground 230

6.6.1 Dynamic Power Distribution 231

6.6.2 Power System Impedance 231

6.6.3 Resonance of Decoupling Capacitance 232

6.6.4 Power Distribution Modeling 232

6.6.5 Switching Noise 233

6.7 Overall Packaged IC Models and Simulation 236

6.7.1 Simulation 237

6.8 Time-Domain Reflectometry 238

6.9 Summary 242

References 242

Exercises 243

7. Thermal Considerations 247

Rick J. Couvillion

7.1 Introduction 247

7.1.1 Heat Sources 247

7.1.2 Approaches to Heat Removal 249

7.1.3 Failure Modes 250

7.2 Heat Transfer Fundamentals 251

7.2.1 Heat Transfer Rate Equations 251

7.2.2 Transient Thermal Response of Components 255

7.2.3 Conduction in Various Shapes 257

7.2.4 Overall Resistance 264

7.2.5 Forced Convection Heat Transfer 268

7.2.6 Natural or Free Convection Heat Transfer 276

7.3 Air Cooling 282

7.4 Liquid Cooling 282

7.4.1 Single-Phase Liquid Cooling 282

7.4.2 Two-Phase Liquid Cooling 282

7.5	Advanced Cooling Methods	286			
7.5.1	Heat Pipes	286			
7.5.2	Thermoelectric Cooling	287			
7.5.3	Microchannel Cooling	288			
7.6	Computer-Aided Modeling	289			
7.6.1	Solids Modeling	289			
7.6.2	Computational Fluid Dynamics	290			
7.6.3	Levels of Decoupling	290			
7.6.4	Typical Results	290			
7.7	Summary	290			
	References	292			
	Appendix: Thermophysical Properties for Heat Transfer Calculations	292			
	Exercises	297			
8.	Mechanical Design Considerations	299			
	William F. Schmidt				
8.1	Introduction	299			
8.2	Deformation and Strain	299			
8.3	Stress	303			
8.4	Constitutive Relations	307			
8.4.1	Elastic Material	307			
8.4.2	Plastic Material	309			
8.4.3	Creep	310			
8.5	Simplified Forms	311			
8.5.1	Plane Stress and Plane Strain	311			
8.5.2	Beams	312			
8.6	Failure Theories	317			
8.6.1	Static Failure	318			
8.6.2	Fracture Mechanics	320			
8.6.3	Fatigue	321			
8.7	Analytical Determination of Stress	323			
8.7.1	Bi-Material Assembly—Axial Effects	323			
8.7.2	Bi-Material Assembly—Bending Effects	328			
8.7.3	Peeling Stress	329			
8.7.4	Tri-Material Assembly	331			
8.8	Numerical Formulations	335			
8.8.1	Finite-Element Method	335			
8.8.2	Commercial Codes	338			
8.8.3	Limitations and Hazards	340			
8.9	Summary	341			
	References	341			
	Bibliography	341			
	Exercises	342			
9.	Discrete and Embedded Passive Devices	349			
	Richard Ulrich				
9.1	Introduction	349			
9.2	Passives in Modern Electronic Systems	350			
9.3	Definitions and Configurations of Passives	354			
9.4	Film-Based Passives	356			
9.5	Resistors	358			
9.5.1	Design Equations	358			
9.5.2	Sizing Embedded Resistors	360			
9.5.3	Materials for Resistors	361			
9.6	Capacitors	363			
9.6.1	Paraelectrics and Ferroelectrics	365			
9.6.2	Sizing Dielectric Areas	367			
9.6.3	Dielectric Materials Used in Capacitors	369			
9.7	Inductors	371			
9.8	Electrical Characteristics of Passives	372			
9.8.1	Modeling Ideal Passives	373			
9.8.2	Modeling Real Capacitors	374			
9.8.3	Differences in Parasitics Between Discrete and Embedded Capacitors	375			
9.8.4	Modeling Real Inductors	377			
9.8.5	Modeling Real Resistors	379			
9.9	Issues in Embedding Passives	379			
9.9.1	Reasons for Embedding Passives	379			
9.9.2	Problems with Embedding Passive Devices	380			
9.10	Decoupling Capacitors	381			
9.10.1	Decoupling Issues	381			
9.10.2	Decoupling with Discrete Capacitors	382			
9.10.3	Decoupling with Embedded Capacitors	383			
9.11	Future of Passives	384			
	References	385			
	Exercises	386			
10.	Electronic Package Assembly	389			
	Tarak A. Railkar and Robert W. Warren				
10.1	Introduction	389			

10.2	Facilities	389	10.8.1	Wafer Bumping	419
10.2.1	Cleanroom Requirements	389	10.8.2	Fluxing	422
10.2.2	Electrostatic Discharge Requirements	391	10.9	Package Sealing/Encapsulation/Coating	425
10.2.3	Moisture Sensitivity Level (MSL) Requirements	392	10.9.1	Hermetic Package Sealing	426
10.2.4	Reflow Temperatures	393	10.9.2	Hermetic Package Testing	426
10.3	Component Handling	393	10.9.3	Nonhermetic Encapsulation	427
10.3.1	Shipping	393	10.10	Package-Level Processes	429
10.3.2	Storage	393	10.10.1	Lead Trim, Form, and Singulation	430
10.3.3	Handling/Processing	394	10.10.2	Solder Ball Attach and Singulation	430
10.4	Surface-Mount Technology (SMT) Assembly	395	10.10.3	Marking	430
10.4.1	Solder Printing and Related Defects	395	10.11	State-of-the-Art Technologies	430
10.4.2	Component Placement	397	10.11.1	3D and Stacked Die	430
10.4.3	Solder Reflow	398	10.11.2	Radio Frequency (RF) Modules	431
10.4.4	Cleaning	399	10.11.3	Microelectromechanical Systems (MEMS) and Microoptoelectromechanical Systems (MOEMS)	432
10.5	Wafer Preparation	399	10.11.4	Nanotechnology	434
10.5.1	Wafer Probing	399	10.12	Summary	435
10.5.2	Wafer Mounting	401		References	435
10.5.3	Wafer Backgrinding/Thinning	401		Exercises	436
10.5.4	Wafer Sawing	402			
10.5.5	Wafer Scribing	403			
10.5.6	Equipment	404			
10.6	Die Attachment	405	11. Design Considerations		437
10.6.1	Epoxy	405	<hr/>		
10.6.2	Thermoplastics and Thermosets	406	J. P. Parkerson and L. W. Schaper		
10.6.3	Solder	407	11.1	Introduction	437
10.6.4	Rework	407	11.2	Packaging and the Electronic System	437
10.6.5	Die-Attach Equipment	408	11.2.1	Packaging Functions	437
10.7	Wirebonding	409	11.2.2	System and Packaging Metrics	438
10.7.1	Thermocompression Wirebonding	409	11.2.3	System Constraints and Trade-Offs	440
10.7.2	Ultrasonic Wirebonding	409	11.2.4	System Partitioning	442
10.7.3	Thermosonic Wirebonding	410	11.3	Trade-Offs Among Packaging Functions	445
10.7.4	Ribbon Bonding	410	11.3.1	Signal Wiring	445
10.7.5	Ball Bonding	410	11.3.2	Power Distribution	452
10.7.6	Wedge Bonding	411	11.3.3	Thermal Management	455
10.7.7	Wirebond Testing	411	11.3.4	Interconnect Testing	456
10.7.8	Tape-Automated Bonding	414	11.4	Trade-Off Design Example	458
10.7.9	Plasma Surface Treatment	415	11.5	Product Development Cycle	460
10.8	Flip-Chip	417	11.5.1	Traditional and Modified Product Cycles	461

- 11.5.2 Market Analysis and Product Specification 463
- 11.5.3 Block Diagram and Partitioning 464
- 11.5.4 Technology Selection 464
- 11.5.5 ASIC/PCB/MCM Design 465
- 11.5.6 Thermal/Mechanical Design 466
- 11.5.7 Test Program Development 466
- 11.5.8 Manufacturing Tooling 467
- 11.5.9 Fabrication/Assembly 467
- 11.5.10 Characterization 467
- 11.5.11 Qualification 467
- 11.5.12 Product Introduction 468
- 11.6 Design Concepts 468
 - 11.6.1 Component Overview 469
 - 11.6.2 Schematic Overview 471
 - 11.6.3 Design Viewpoint 474
 - 11.6.4 Back Annotation 475
 - 11.6.5 Simulation and Evaluation 476
- 11.7 PCB/MCM Board Design Process 477
 - 11.7.1 PCB Design Flow 477
 - 11.7.2 Librarian 477
 - 11.7.3 Package 479
 - 11.7.4 Layout 479
 - 11.7.5 Fablink 481
 - 11.7.6 Summary of Design Concepts 484
- 11.8 Summary 484
 - References 484
 - Bibliography 485
 - Exercises 485

12. Radio Frequency and Microwave Packaging 487

Fred Barlow and Aicha Elshabini

- 12.1 Introduction and Background 487
 - 12.1.1 Nature of High-Frequency Circuits 487
 - 12.1.2 Applications of High-Frequency Circuits 488
 - 12.1.3 Basic Concepts 490
- 12.2 Transmission Lines 494

- 12.2.1 Transmission Line Modes 495
- 12.2.2 System-Level Transmission Lines 496
- 12.2.3 Planar Transmission Lines 499
- 12.2.4 Discontinuities 505
- 12.3 High-Frequency Circuit Implementation 510
 - 12.3.1 Material Considerations 510
 - 12.3.2 Microwave Monolithic Integrated Circuits 513
 - 12.3.3 MIC Technologies 513
- 12.4 Lumped-Element Components 515
 - 12.4.1 Capacitors 515
 - 12.4.2 Inductors 516
 - 12.4.3 Resistors and Terminations 518
- 12.5 Distributed Components 518
 - 12.5.1 Impedance-Matching Devices 518
 - 12.5.2 Filters 519
 - 12.5.3 Power Dividers 520
 - 12.5.4 Couplers 522
- 12.6 Simulation and Circuit Layout 523
- 12.7 Measurement and Testing 525
- 12.8 Frequency-Domain Measurements 525
 - 12.8.1 Measurement Systems 525
 - 12.8.2 Probing Hardware and Connectors 526
- 12.9 Time-Domain Measurements 527
- 12.10 Design Example 528
- 12.11 Summary 531
 - References 531
 - Exercises 535

13. Power Electronics Packaging 537

Alexander B. Lostetter and Kraig Olejniczak

- 13.1 Introduction 537
- 13.2 Semiconductor Power Device Technology 537
 - 13.2.1 Ideal and Nonideal Power Switching 538
 - 13.2.2 Power Diodes 540

- 13.2.3 Thyristors 541
- 13.2.4 Power Bipolar Junction Transistors 542
- 13.2.5 Power MOSFETs 542
- 13.2.6 Insulated Gate Bipolar Transistors 542
- 13.2.7 Static Induction Transistors (SITs) 543
- 13.2.8 Silicon Carbide Semiconductor Devices 543
- 13.3 Commercially Available Power Packages 547
 - 13.3.1 Discrete Power Device Packages 547
 - 13.3.2 Multichip Power Modules (MCPMs) and Completely Integrated Solutions 548
 - 13.3.3 Thermal Performance of Commercial Packages [53–58] 552
- 13.4 Power Packaging Design Methodology 561
 - 13.4.1 Overall System Design Philosophies 561
 - 13.4.2 Substrate Selection 563
 - 13.4.3 Baseplate and Heat Spreader Selection 565
 - 13.4.4 Die-Attach Methods [62–64] 565
 - 13.4.5 Wirebonding [65] 570
 - 13.4.6 Thermal Design 573
 - 13.4.7 Electromagnetic Interference (EMI) and Electromagnetic Compliance (EMC) 576
 - 13.4.8 High-Temperature Power Electronics 576
- 13.5 Summary 577
- References 577
- Exercises 579

- 14.2.2 Anatomy of an MCM 588
- 14.2.3 Planar MCM Approaches 591
- 14.3 Three-Dimensional Systems 599
 - 14.3.1 Defining Characteristics of 3D Systems 599
 - 14.3.2 Die and Package Stacks 602
 - 14.3.3 MCM Stacks 605
 - 14.3.4 Folding Approaches 607
- 14.4 Options in Multichip Packaging 608
 - 14.4.1 Yield/Known Good Die 608
 - 14.4.2 Process Compatibility 609
 - 14.4.3 Density Metrics in 2D and 3D Packaging 609
 - 14.4.4 Wiring Density 609
 - 14.4.5 Input/Output 610
 - 14.4.6 Electrical Performance and Substrate Selection 613
 - 14.4.7 Thermal Management 613
 - 14.4.8 Testability 615
 - 14.4.9 System in a Package Versus System on a Chip 615
- 14.5 Emerging Trends in Density Scaling 615
 - 14.5.1 Method 1: For Regular and/or Low-Pincount Assemblies 617
 - 14.5.2 Method 2: For Moderately Complex Pincount Assemblies 618
 - 14.5.3 Method 3: For Moderately Complex Pincount Assemblies 619
 - 14.5.4 Issues in Ultradense Packaging 619
- 14.6 Summary 621
- References 622
- Exercises 623

14. Multichip and Three-Dimensional Packaging 583

James Lyke

- 14.1 Introduction 583
 - 14.1.1 Brief History of Multichip Packaging 583
 - 14.1.2 Motivations for Multichip Packaging 585
- 14.2 Packaging Hierarchy and Taxonomy 588
 - 14.2.1 Hierarchy 588

15. Packaging of MEMS and MOEMS: Challenges and a Case Study 625

Ajay P. Malshe, Volkan Ozguz and John Patrick O'Connor

- 15.1 Introduction 625
- 15.2 Background 625
 - 15.2.1 Mixed Signals, Mixed Domains, and Mixed Scales Packaging: Toward the Next-Generation

	Application-Specific Integrated Systems	626			
15.2.2	Microelectromechanical Systems	626			
15.3	Challenges in Mems Integration	628			
15.3.1	Release and Stiction	630			
15.3.2	Dicing	631			
15.3.3	Die Handling	631			
15.3.4	Wafer-Level Encapsulation	631			
15.3.5	Stress	632			
15.3.6	Outgassing	632			
15.3.7	Testing	633			
15.3.8	State-of-the-Art in MEMS Packaging	633			
15.3.9	Future Directions	635			
15.4	Packaging Considerations and Guidelines Related to the Digital Micromirror Device	636			
15.4.1	Introduction and Background to MOEMS and Particularly DMD Devices	636			
15.4.2	Parameters Influencing DMD Packaging	637			
15.4.3	DMD Package Design	640			
15.4.4	DMD Hermetic Package Assembly	646			
15.5	Future Packaging Challenges	647			
	References	648			
	Exercises	650			
16.	Reliability Considerations	651			
	<hr/>				
	Richard Ulrich				
16.1	Introduction	651			
16.1.1	Definitions	651			
16.1.2	Patterns of Failure	653			
16.1.3	Coverage in This Chapter	654			
16.2	Failure Mechanisms	655			
16.2.1	Corrosion	656			
16.2.2	Mechanical Stress	659			
16.2.3	Electrical Stress	660			
16.2.4	Techniques for Failure Analysis	660			
16.3	Accelerated Testing	661			
16.3.1	Accelerated Environmental Testing	663			
16.3.2	Electrostatic Discharge Accelerated Testing	666			
16.3.3	Other Accelerated Tests	666			
16.3.4	Test Structures	667			
16.4	Reliability Metrology	668			
16.4.1	Failure Rate, MTBF, and FITs	668			
16.4.2	Reliability Functions	668			
16.4.3	Weibull Distribution	674			
16.4.4	Normal Distribution	677			
16.4.5	Failure Distributions and the Bathtub Curve	680			
16.5	Failure Statistics for Microelectronic Systems	681			
16.5.1	Predicting Failure in Components That Have Multiple Failure Modes	683			
16.6	Industrial Practice of Reliability Science for Microelectronics	684			
	Bibliography	684			
	Exercises	684			
17.	Cost Evaluation and Analysis	691			
	<hr/>				
	Terry R. Collins, Scott J. Mason, and Heather Nachtmann				
17.1	Introduction	691			
17.2	Product Cost	691			
17.2.1	Direct Costs	692			
17.2.2	Indirect Costs	692			
17.2.3	Traditional Volume-Based Costing	692			
17.2.4	Activity-Based Costing	694			
17.3	Break-even Analysis	696			
17.3.1	Linear Break-even Analysis	696			
17.3.2	Piecewise Linear Break-even Analysis	698			
17.4	Learning Curve Relationships	698			
17.4.1	Determining Exponent Values for Improvement Rates	700			
17.4.2	Learning Curve Examples	702			
17.5	Forecasting Models	703			

17.5.1 Mean-Squared Error (MSE) 704
 17.5.2 Mean Absolute Deviation (MAD) 704
 17.5.3 Mean Percentage Error (MPE) 704
 17.5.4 Mean Absolute Percentage Error (MAPE) 705
 17.5.5 Moving Average 705
 17.5.6 Forecasting Sales Based on Historical Data 706
 17.5.7 Exponential Smoothing 707
 17.5.8 Least-Squares Regression 712
 17.6 Comparative Analysis 714
 17.6.1 Capital Project Selection and Evaluation 715
 17.6.2 Replacement Analysis 716
 17.7 Sensitivity Analysis 717
 17.7.1 Single-Parameter Sensitivity Analysis 718
 17.7.2 Optimistic–Pessimistic Sensitivity Analysis 719
 17.8 Summary 720
 References 721
 Exercises 721

18. Analytical Techniques for Materials Characterization 725

Emily A. Clark, Ingrid Fritsch, Seifollah Nasrazadani, and Charles S. Henry

18.1 Overview 725
 18.2 X-Ray Diffraction 725
 18.2.1 Summary 728
 18.2.2 Basic Principles 728
 18.2.3 Instrumentation 729
 18.2.4 Practical Considerations and Applications 731
 18.3 Raman Spectroscopy 734
 18.3.1 Summary 734
 18.3.2 Basic Principles 735
 18.3.3 Instrumentation 735
 18.3.4 Practical Considerations and Applications 736

18.4 Scanning Probe Microscopy 740
 18.4.1 Summary 740
 18.4.2 STM Principles and Instrumentation 740
 18.4.3 SFM Principles and Instrumentation 741
 18.4.4 Practical Considerations and Applications 742
 18.5 Scanning Electron Microscopy and Energy Dispersive X-ray Spectroscopy 744
 18.5.1 Summary 744
 18.5.2 Basic Principles 745
 18.5.3 Instrumentation 746
 18.5.4 Practical Considerations and Applications 748
 18.6 Confocal Microscopy 750
 18.6.1 Summary 750
 18.6.2 Basic Principles 750
 18.6.3 Instrumentation 750
 18.6.4 Practical Considerations and Applications 751
 18.7 Auger Electron Spectroscopy 752
 18.7.1 Summary 752
 18.7.2 Basic Principles 753
 18.7.3 Instrumentation 757
 18.7.4 Practical Considerations and Applications 759
 18.8 X-ray Photoelectron Spectroscopy 766
 18.8.1 Summary 766
 18.8.2 Basic Principles 766
 18.8.3 Instrumentation 769
 18.8.4 Practical Considerations and Applications 770
 18.9 Secondary Ion Mass Spectrometry 775
 18.9.1 Summary 775
 18.9.2 Basic Principles 776
 18.9.3 Instrumentation 778
 18.9.4 Practical Considerations and Applications 782
 References 786
 Exercises 790

Index 793